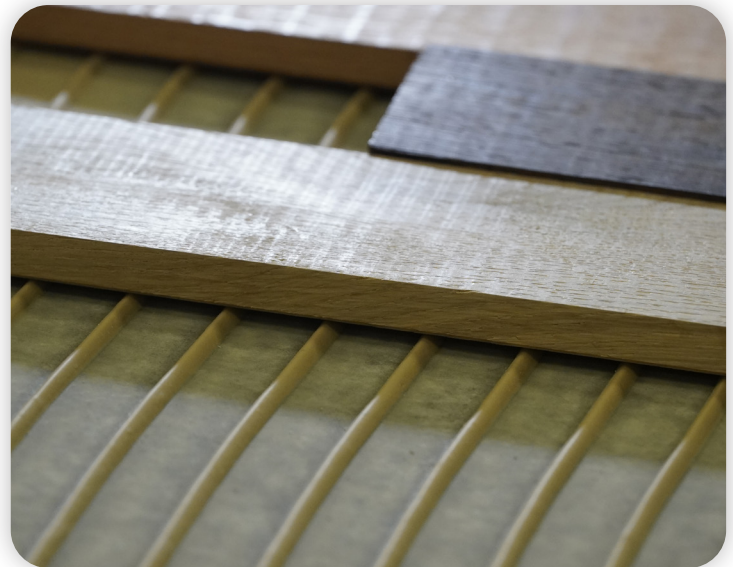


Lechner

SOLUTIONS FOR PROFESSIONAL CONSTRUCTION



FIELDS OF APPLICATION

-  RESILIENT LINE
-  MARINE LINE
-  EQUIPMENT AND ACCESSORIES LINE
-  WOOD LINE
-  ARTIFICIAL GRASS LINE

SMP BOND 200

SINGLE-COMPONENT RIGID ADHESIVE FOR PARQUET WITH SMP TECHNOLOGY

DESCRIPTION AND USES PRODUCT FOR PROFESSIONAL USE ONLY

ISO 17178:2013 compliant "rigid", single-component, moisture-curing, solvent-free and isocyanate-free adhesive, made of silane terminated polymers. Suitable for gluing solid wood and multilayer parquet (2 or 3 layers) on absorbent and non-absorbent substrates and on heated screeds. Quick setting product, with high shear strength and excellent adhesion to substrates.

PRODUCT FEATURES

**Application**

Lechner no. 6 notched trowel

**Suitable for indoor use****Suitable for heating substrates****Workability time**

40 minutes

Dry-to-walk-on time

12-18 hours

Final setting time

24-48 hours

**Appearance**

Paste

**Color**

Hazelnut

**Storage**

12 months in the original sealed packaging

**Chemical base**

Modified silane polymer

**Use**

900-1,400 g/m²

**Operating temperature**

+15 - +25°C

**Cleaning**

Tools with Solvent CH 500/Residue with Cleancoll or Eco Cleancoll (while the product is wet)

DIRECTIONS FOR USE

The substrate must be compact, sound, clean, cured, permanently dry and free from detaching substances such as oils, waxes, excess dust, etc. If there are cracks or crevices, these must be repaired with SIGEPOX. Maximum permissible moisture content:

- Cementitious substrates max 2%; with underfloor heating 1.7%

- Gypsum or anhydrite substrates max 0.5%; with underfloor heating 0.2%.

Check that there is no rising moisture, always place an insulating barrier between the ground and the load-bearing screed. We do not recommend laying upon screeds in contact with moisture and/or evaporative flows in order to avoid the onset of alkaline hydrolysis. In the case of dusty, excessively absorbent or insufficiently solid cementitious screeds, intervention using suitable primers such as: PU series, EPOPRIMER, PRIMER SIL, PRIMER AC PLUS is necessary. On stone and non-absorbent surfaces such as ceramics, treating the surface with hot water and soda before rinsing thoroughly is necessary. Applying PROMOX to the clean, dry surface to improve adhesion is advised. Gypsum or anhydrite substrates must be sanded, freed of dust and primed according to the manufacturer's instructions. Substrates that have an insufficiently flat or raised laying surface may be leveled with cement-based leveling agents such as FIBRODUR or LEVELFAST (minimum thickness 3mm). Non-heated substrates possessing an excessive degree of humidity (max 5%) must be waterproofed with the appropriate primers such as: PU, EPOPRIMER, or TRIX series according to the absorbency of the surface.

Heated substrates may only be consolidated but not waterproofed (if necessary, contact the Technical Office). For direct application on wooden floors, check the adhesion of the old wood to the screed, then proceed with sanding the surface of the wood, in order to remove the painted layer, before removing dust ahead of subsequent gluing. Before laying, make sure that the rooms have windows. Check that parquet moisture is between 7 and 11%. Apply the adhesive to the substrate with a suitably-sized notched trowel, working it in order to incorporate any residual surface dust. Lay the components - taking care not to put them against the perimeter walls to encourage their natural dimensional variation in the subsequent "acclimation" phase - by pressing them in order to ensure their contact with the substrate before the glue hardens and creates a "skin" (within approx. 40 minutes of application) which would compromise their adhesive properties. Avoiding gluing boards along their sides is advised. Gluing boards along their sides is not advised.

In order to avoid product's hardening, immediately after using the required quantity, seal the packaging by applying the special protective sheet in direct contact with the surface. Diluting the product in any way is not recommended.

ADDITIONAL INFORMATION

The application and gluing times indicated refer to an ambient temperature of +20°C and a relative humidity of 50%. Acclimate the product at usage temperature. Before proceeding with the planing, sanding and subsequent finishing of the wooden floor, waiting for the parquet to stabilize is necessary. SMP BOND 200 can be removed with a dry cloth when still fresh; alternatively, it may be removed with CLEANCOLL or ECO CLEANCOLL by first carrying out a test on a not yet laid wooden piece. Once the adhesive has hardened, it can only be removed mechanically.

INSTRUCTIONS

SAFETY AND DISPOSAL: Before using product, consult the relevant safety data sheet. Gloves are recommended during use. Ventilate the room during and after use. Comply with the safety regulations in force. Do not dispose of any residue in the ground, waterways or drains. For disposal of the product, as well as any other resultant waste, please strictly comply with the provisions of Legislative Decree 152/2006 and subsequent amendments (Consolidated Environmental Law). For further information, please contact our Technical Assistance Office. The content of this current sheet supplements and replaces the previous version, rendering it null and void.

WARNINGS: The data provided in this technical data sheet reflect our best theoretical and practical knowledge. However, it is not possible for us to consider every detail, therefore this information should not be considered as binding. In case of doubt, contact our technical offices.